

# EC2625TS-85.768M

<b>Lead Free</b>  <b>COMPLIANT</b>	<b>RoHS</b>  <b>COMPLIANT</b>	<b>ChinaRoHS</b>  <b>COMPLIANT</b>	<b>REACH</b> <b>SVHC 161</b> Dec 17, 2014 <b>COMPLIANT</b>
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## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 85.768MHz  $\pm 25$ ppm  $-10^{\circ}\text{C}$  to  $+70^{\circ}\text{C}$

## ELECTRICAL SPECIFICATIONS

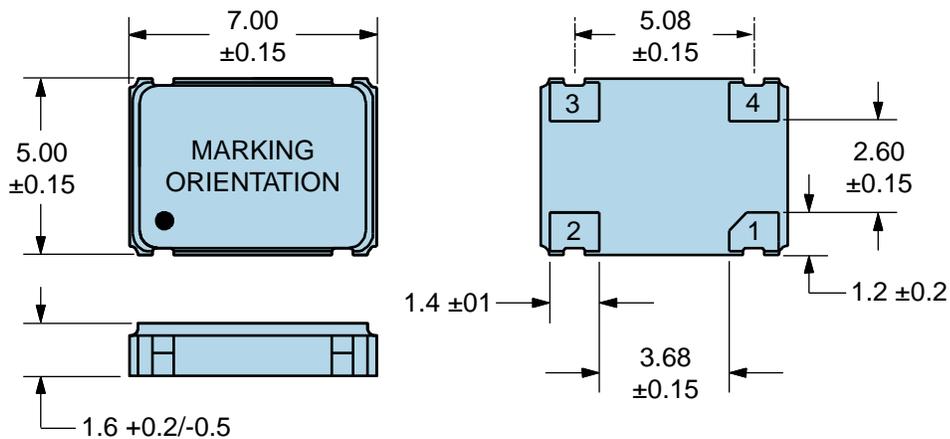
<b>Nominal Frequency</b>	85.768MHz
<b>Frequency Tolerance/Stability</b>	$\pm 25$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at $25^{\circ}\text{C}$ , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at $25^{\circ}\text{C}$ , Shock, and Vibration)
<b>Aging at <math>25^{\circ}\text{C}</math></b>	$\pm 5$ ppm/year Maximum
<b>Operating Temperature Range</b>	$-10^{\circ}\text{C}$ to $+70^{\circ}\text{C}$
<b>Supply Voltage</b>	3.3Vdc $\pm 10\%$
<b>Input Current</b>	40mA Maximum
<b>Output Voltage Logic High (Voh)</b>	90% of Vdd Minimum (IOH= $-8$ mA)
<b>Output Voltage Logic Low (Vol)</b>	10% of Vdd Maximum (IOL= $+8$ mA)
<b>Rise/Fall Time</b>	3nSec Maximum (Measured at 20% to 80% of waveform)
<b>Duty Cycle</b>	50 $\pm 10$ (%) (Measured at 50% of waveform)
<b>Load Drive Capability</b>	15pF Maximum
<b>Output Logic Type</b>	CMOS
<b>Pin 1 Connection</b>	Tri-State (High Impedance)
<b>Tri-State Input Voltage (Vih and Vil)</b>	$+0.7$ Vdd Minimum or No Connect to Enable Output, $+0.3$ Vdd Maximum to Disable Output (High Impedance)
<b>Standby Current</b>	10 $\mu$ A Maximum (Disabled Output: High Impedance)
<b>RMS Phase Jitter</b>	1pSec Maximum (12kHz to 20MHz offset frequency)
<b>Start Up Time</b>	10mSec Maximum
<b>Storage Temperature Range</b>	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Mechanical Shock</b>	MIL-STD-883, Method 2002, Condition B
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL 1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)

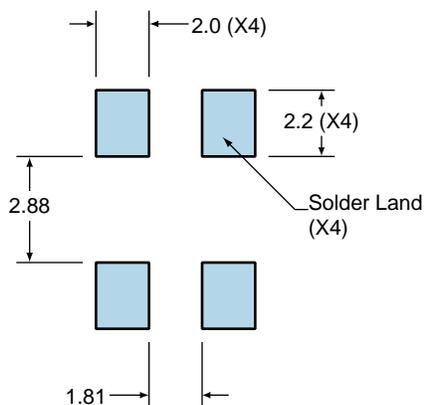


PIN	CONNECTION
1	Tri-State
2	Ground/Case Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	85.768M
3	XXXXXX XXXXXX=Ecliptek Manufacturing Identifier

## Suggested Solder Pad Layout

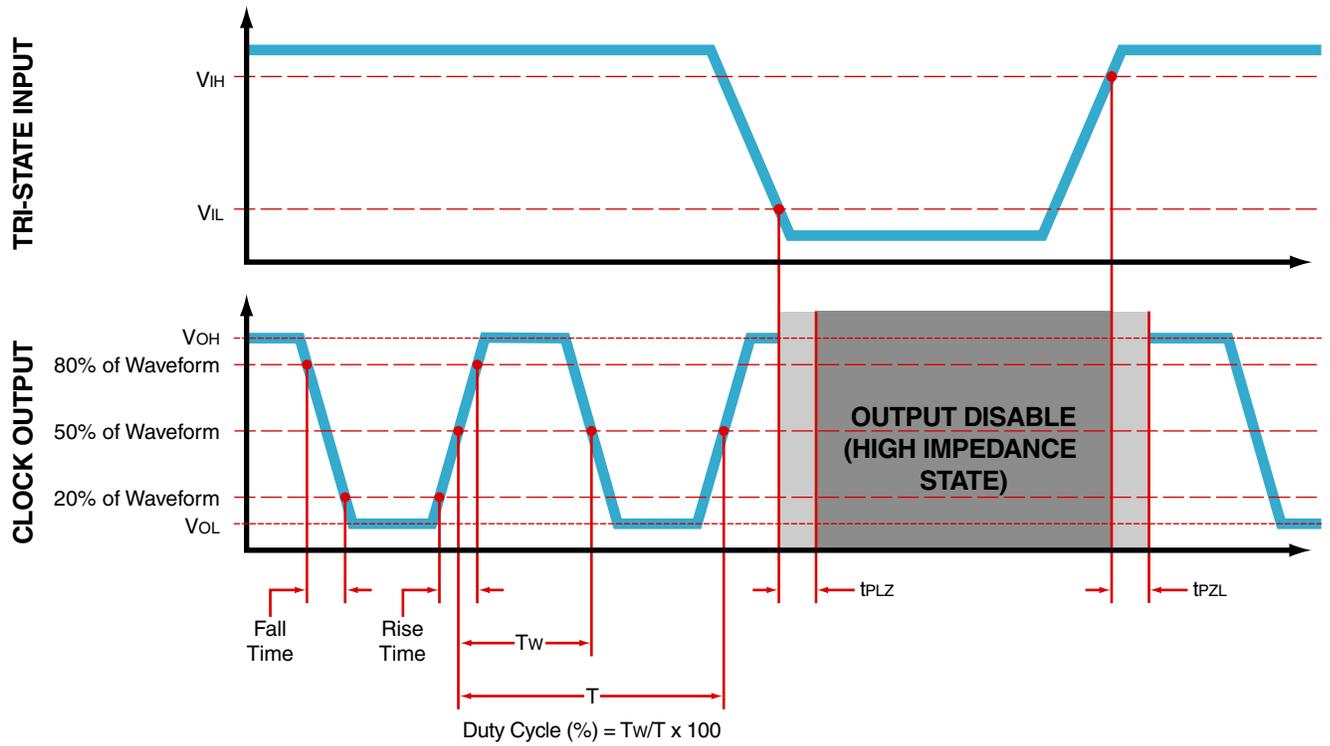
All Dimensions in Millimeters



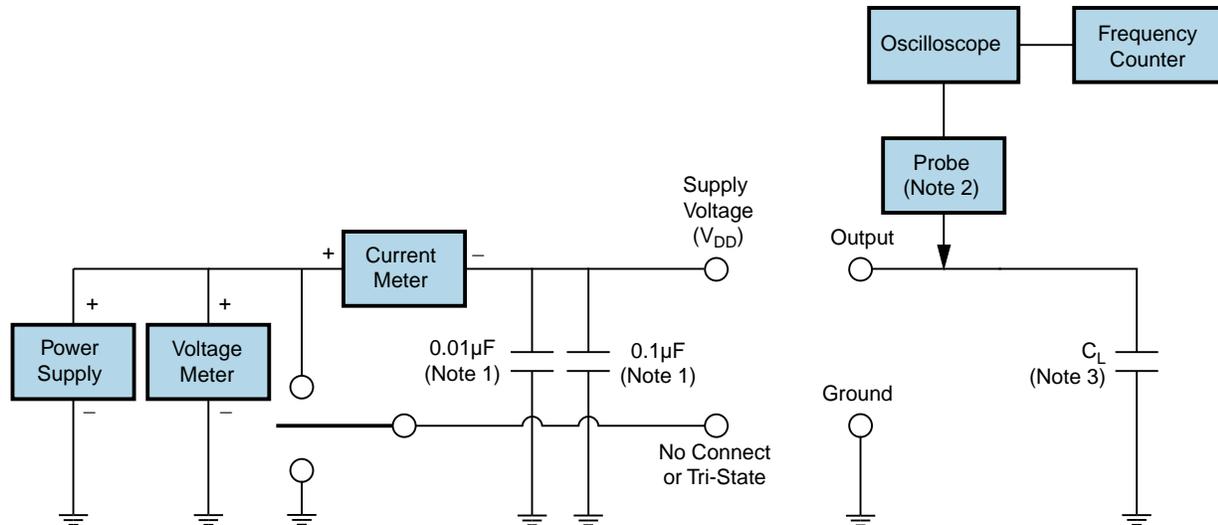
All Tolerances are ±0.1

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## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



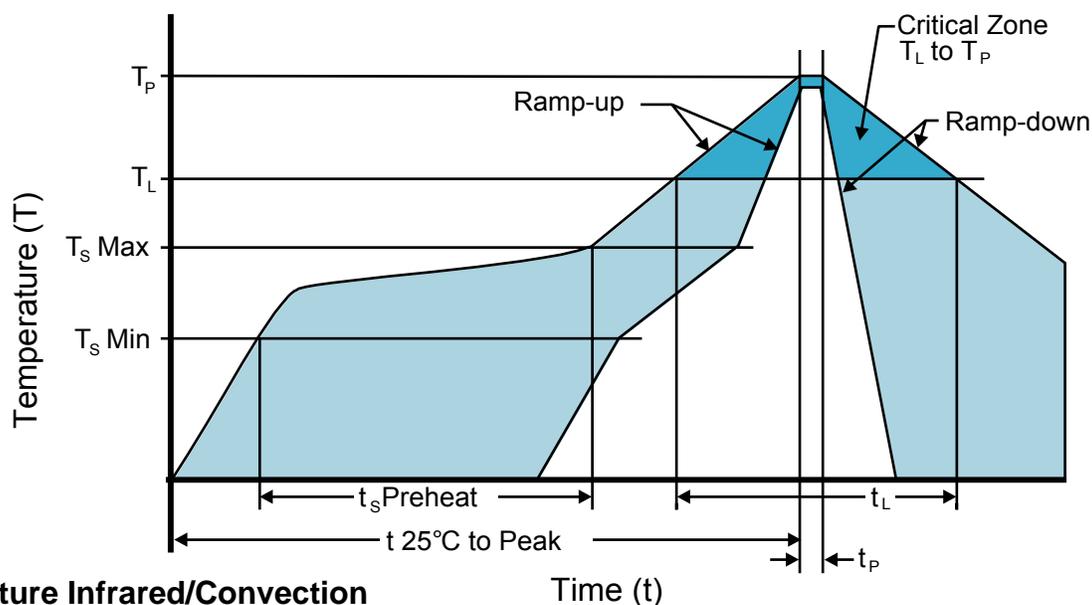
Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods

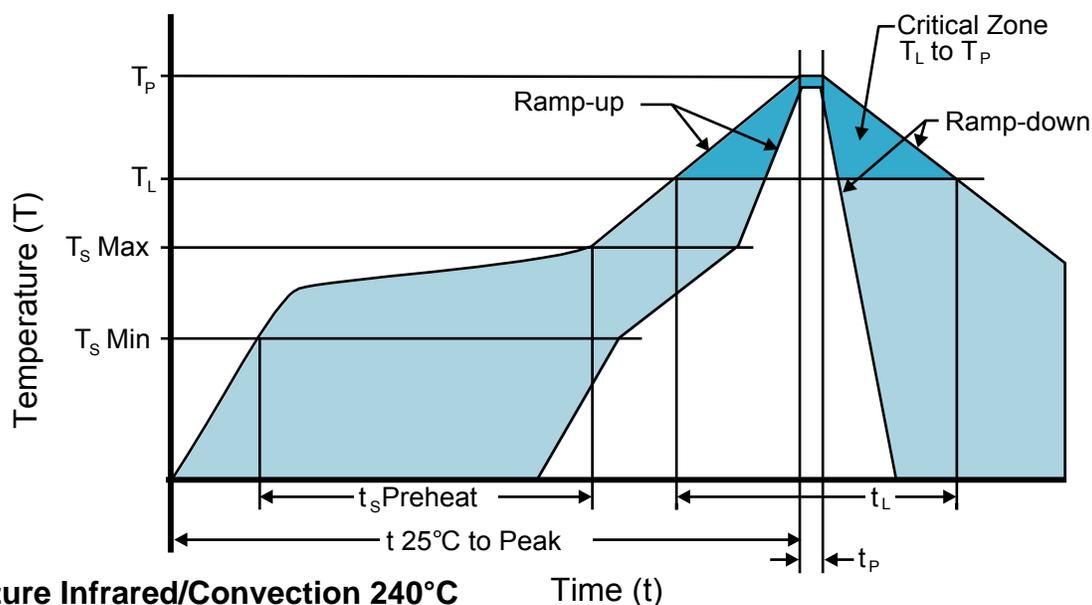


### High Temperature Infrared/Convection

<b>Ts MAX to TL (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
<b>Ramp-up Rate (TL to TP)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds
<b>Peak Temperature (TP)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (TP Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (tp)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

**$T_s$  MAX to  $T_L$  (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum ( $T_s$  MIN) N/A  
 - Temperature Typical ( $T_s$  TYP) 150°C  
 - Temperature Maximum ( $T_s$  MAX) N/A  
 - Time ( $t_s$  MIN) 60 - 120 Seconds

**Ramp-up Rate ( $T_L$  to  $T_P$ )** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 150°C  
 - Time ( $t_L$ ) 200 Seconds Maximum

**Peak Temperature ( $T_P$ )** 240°C Maximum

**Target Peak Temperature ( $T_P$  Target)** 240°C Maximum 2 Times / 230°C Maximum 1 Time

**Time within 5°C of actual peak ( $t_p$ )** 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

**Additional Notes** Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)